

**REMARKS/ARGUMENTS**

These remarks are in response to the Official Action mailed April 15, 2005.

A petition for a three-month extension of the shortened statutory time period for response to said Official Action up to and including October 15, 2005, is transmitted herewith.

A Request For Continued Examination (RCE) is also submitted herewith.

As an initial matter, Applicant acknowledges that claims 6 and 7 have been deemed to contain patentable subject matter.

In the Official Action, claim 1 is rejected under 35 U.S.C. § 102(a) as being anticipated by U.S. Patent No. 6,200,134 to *Haba* et al. The Examiner contends that *Haba* discloses all of the limitations within claim 1. Applicant respectfully traverses the Examiner's contention and requests reconsideration and allowance.

Claim 1 of the present application includes the recitation that electrically-conductive material is deposited in the vias without seeding the vias. This recitation was included within the claims in the Official Action dated February 18, 2005. But the Examiner still maintains his rejection and further argues that *Haba* teaches such a recitation. The Examiner has pointed to column 11, lines 8-11 as disclosing depositing a conductive material in a via without seeding the via. Applicant asserts that the passage within column 11 does not disclose such a recitation. The text specifically states that: "the ribs 156 which support the tabs or tines 146 may be seeded and plated if desired, but not required, to provide the metal layer 142 at the same time as the exposed surfaces 140 surrounding the throughhole 136 are plated."

During numerous telephone conversations, the Applicant has argued that this text is limited to either seeding and plating the ribs or not seeding and not plating the ribs. The reference does not disclose placing an electrically-conductive material within a via without seeding as an option. Although Applicant has maintained his vigilance regarding this matter, the Examiner has not been persuaded and still maintains that the above-quoted passage discloses plating the ribs without seeding.

Applicant notes that the "seeded" and "plated" are connected by the word "and" and that the text describing the option "if desired, but not required", follows the word "plated" and does not follow the word "seeded." Therefore, according to Applicant's interpretation, *Haba* teaches seeding and plating the ribs or not seed and not plating the ribs. But definitely does not teach plating the ribs without seeding them.

Even assuming that the Examiner is correct for a moment, *Haba* still does not disclose disposing an electrically-conductive material within a via without seeding. This is because the via to which the Examiner refers to not only includes the ribs 156 of *Haba* but also the exposed surfaces 140 of the dielectric layer 102. Once again, the particular recitation at issue includes depositing electrically-conductive material within the via without seeding as included in claim 1. Therefore, the entire via must not be seeded. At column 8, lines 52-60, *Haba* specifically discloses that the "exposed surfaces 140 surrounding the through hole are seeded with a suitable seeding solution which is known for electroless and/or electroplating a dielectric material. The seeded surfaces 140 are subjected to electroless and electroplating to form a continuous metal layer 142 within the throughhole 136." Therefore, even if one were to make the argument that the ribs are not seeded but are plated, the via is still seeded as a result of the exposed surface being seeded. Applicant pointed

this out to the Examiner but the Examiner maintained that the exposed surfaces 140, as included within column 11, are provided with the metal layer at the same time as the ribs 156. Applicant is unsure as to the importance of this issue as regardless of whether they are made at the same time or not, *Haba* specifically discloses seeding the exposed surfaces. The fact that *Haba* talks about the exposed surface having a metal layer 142 provided at the same time the ribs are provided with a metal layer does not remove the fact that the exposes surfaces are seeded provide to the metal layer being formed.

As such, Applicant asserts that claim 1 is in condition for allowance and should be deemed patentable.

Claims 3-5 are rejected under 35 U.S.C. § 103(a) as being unpatentable over *Haba* in view of U.S. Patent No. 6,222,136 to *Appelt* et al. Claim 3 includes the same limitation regarding depositing an electrically-conductive material in the vias without seeding the vias. *Appelt* is cited for teaching the step of applying a first resist to the top metal layer, applying a second resist to a bottom layer and patterning the first resist and second resist in the same step to form first openings in the first resist and second resist. *Appelt* does not disclose depositing an electrically-conductive feature within the via without seeding the via. Therefore, claim 3, as well as claims 4 and 5, which depend from claim 3, should also be deemed to contain patentable subject matter.

In view of the above, each of the presently pending claims in this application is believed to be in immediate condition for allowance. Accordingly, the Examiner is respectfully requested to withdraw the outstanding rejection of the claims and to pass this application to issue.

If, however, for any reason the Examiner does not believe that such action can be taken at this time, it is respectfully requested that the examiner telephone Applicant's

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attorney at (908) 654-5000 in order to overcome any additional objections which the Examiner might have.

If there are any additional charges in connection with this requested amendment, the Examiner is authorized to charge Deposit Account No. 12-1095 therefor.

Dated: October 17, 2005

Respectfully submitted,

By 

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